

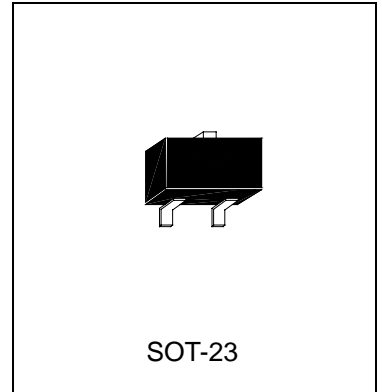


HMBT5087

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HMBT5087 is designed for low noise, high gain, general purpose amplifier applications.



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 225 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage -50 V
VCEO Collector to Emitter Voltage..... -50 V
VEBO Emitter to Base Voltage..... -3V
IC Collector Current -50 mA

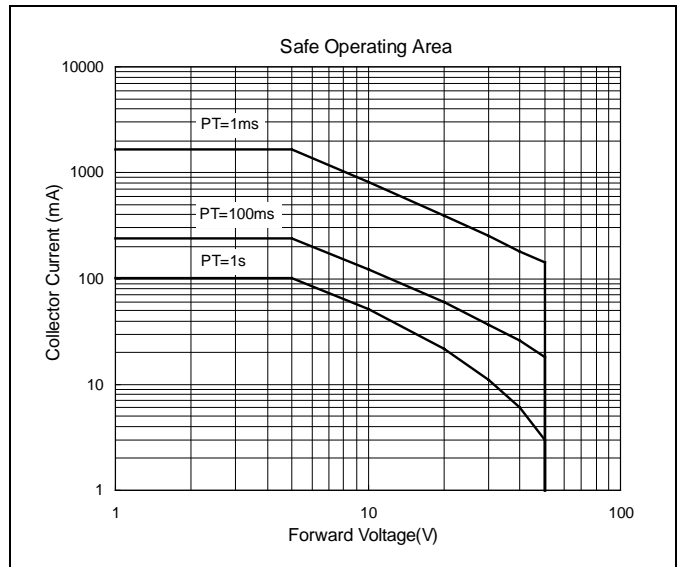
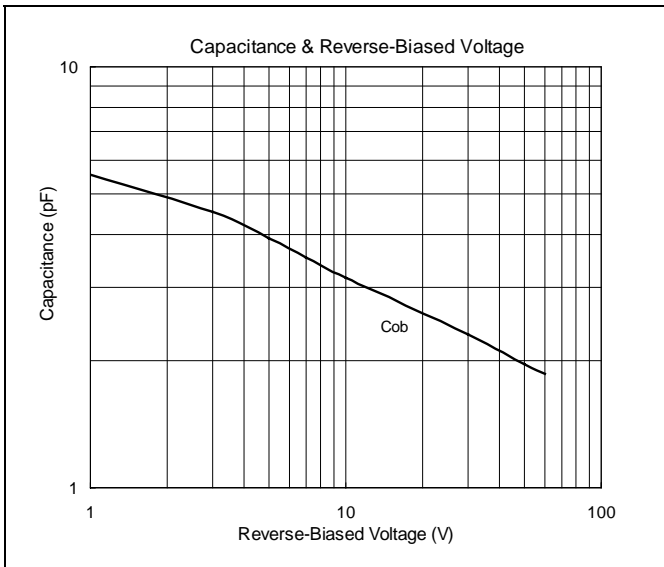
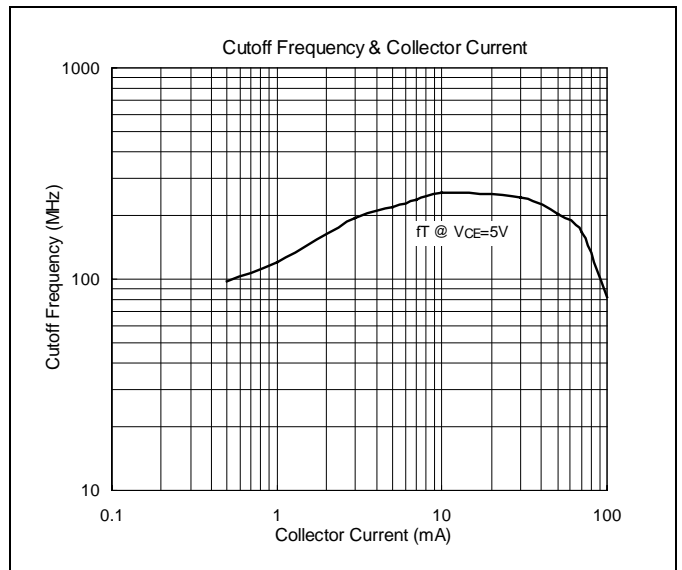
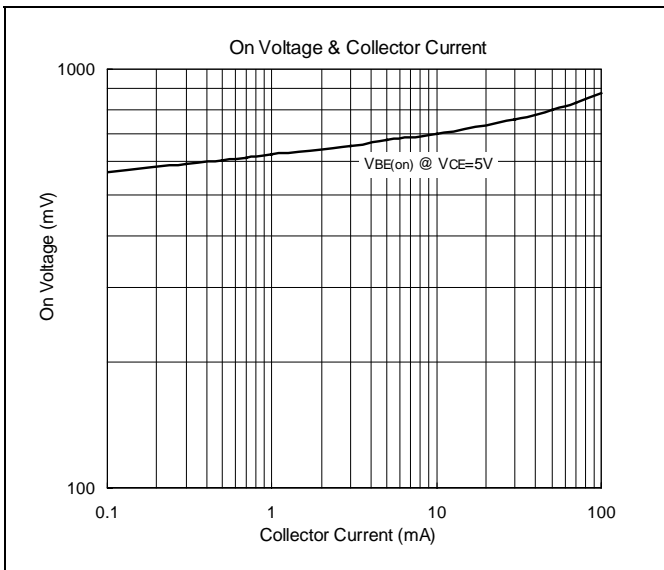
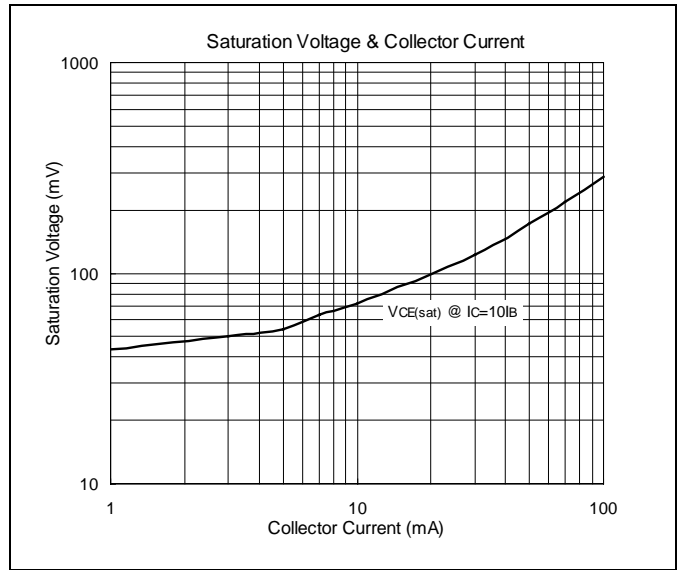
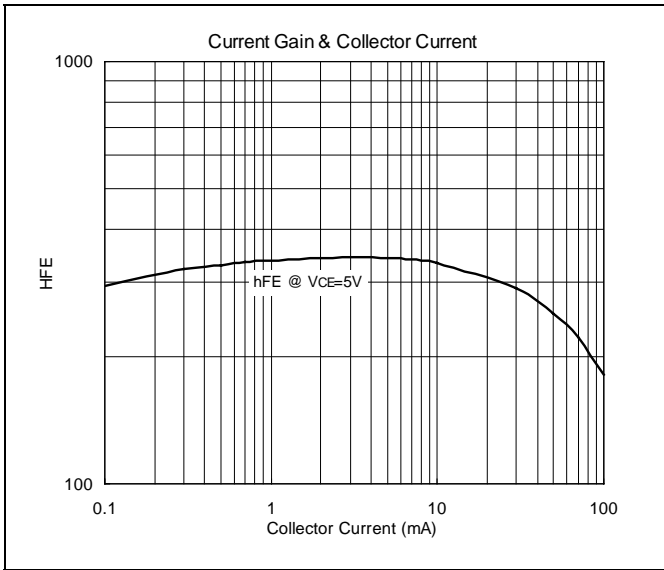
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-50	-	-	V	IC=-100uA
BVCEO	-50	-	-	V	IC=-1mA
BVEBO	-3	-	-	V	IE=-10uA
ICBO1	-	-	-10	nA	VCB=-10V
ICBO2	-	-	-50	nA	VCB=-35V
*VCE(sat)	-	-	-300	mV	IC=-10mA, IB=-1mA
*VBE(sat)	-	-	-850	mV	IC=-10mA, IB=-1mA
*hFE1	250	-	800		VCE=-5V, IC=-0.1mA
*hFE2	250	-	-		VCE=-5V, IC=-1mA
*hFE3	250	-	-		VCE=-5V, IC=-10mA
fT	40	-	-	MHz	VCE=-5V, IC=-0.5mA, f=100MHz
Cob	-	-	4.0	pF	VCB=-5V, f=100KHz

*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

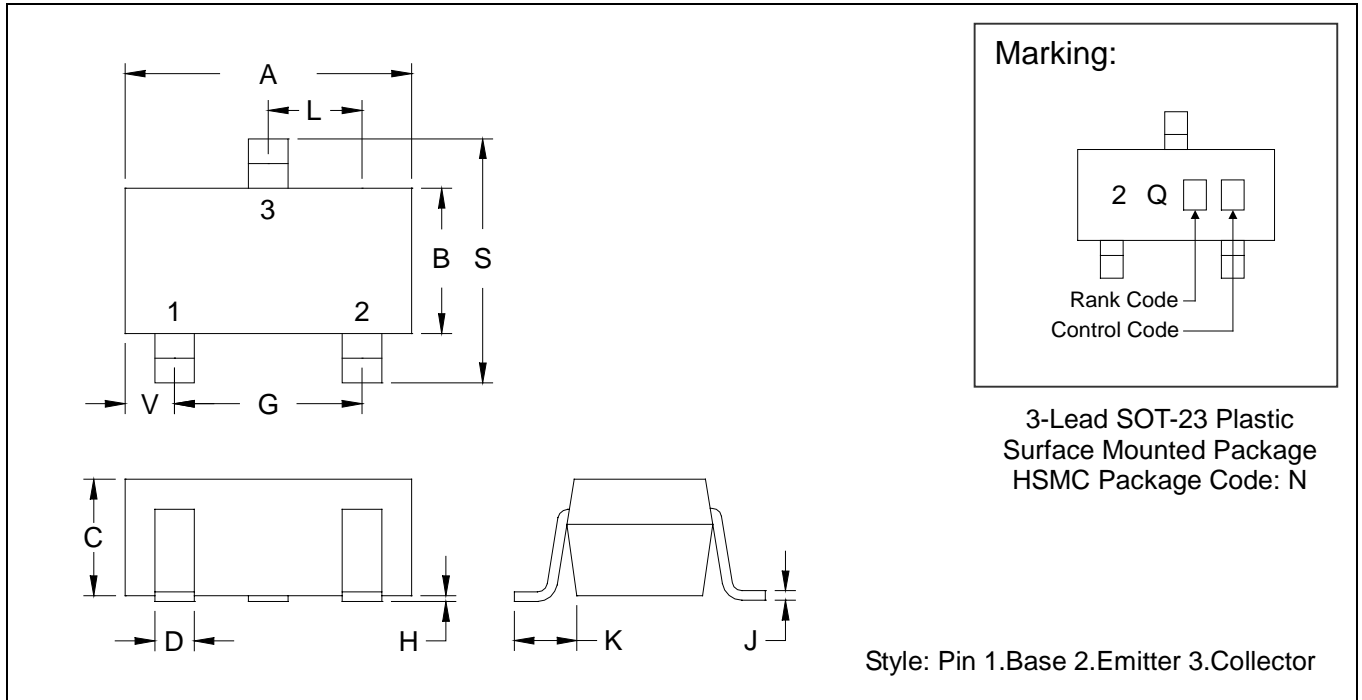


Characteristics Curve





SOT-23 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1102	0.1204	2.80	3.04	J	0.0034	0.0070	0.085	0.177
B	0.0472	0.0630	1.20	1.60	K	0.0128	0.0266	0.32	0.67
C	0.0335	0.0512	0.89	1.30	L	0.0335	0.0453	0.85	1.15
D	0.0118	0.0197	0.30	0.50	S	0.0830	0.1083	2.10	2.75
G	0.0669	0.0910	1.70	2.30	V	0.0098	0.0256	0.25	0.65
H	0.0005	0.0040	0.013	0.10					

- Notes: 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
 2.Controlling dimension: millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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